

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Eun-woo JEONG	11/29/2007
Yong-gwang WON	11/29/2007
RECEIVING PARTY DATA	
Name:	Samsung Electronics Co., Ltd.
Street Address:	416 Maetan-dong, Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11948293
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NAME OF SUBMITTER:	James J. Merrick
Total Attachments: 3	
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CH \$40.00 11948293

ASSIGNMENT

WHEREAS We, **Eun-woo JEONG** of 932-5 Sinjeong 5-dong, Yangcheon-gu, Seoul, Republic of Korea and **Yong-gwang WON** of #102-1302 Life Town APT, Ssangyong-dong, Cheonan-si, Chungcheongnam-do, Republic of Korea (hereinafter referred to as "ASSIGNORS") have invented certain new and useful improvements in:

SEMICONDUCTOR CHIP PACKAGE, PRINTED CIRCUIT BOARD ASSEMBLY INCLUDING THE SAME AND MANUFACTURING METHODS THEREOF

which claims priority to Korea Application No. 10-2006-0120478, filed on December 1, 2006, and for which We are about to file or have filed an application for Letters Patent of the United States;

AND WHEREAS, **Samsung Electronics Co., Ltd.** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Korea having a place of business at **416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea** is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will,

at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: November 29, 2007



Eun-woo JEONG

L.S.

Date: _____

Yong-gwang WON

L.S.

at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: _____

Eun-woo JEONG L.S.

Date: November 29, 2007

Yong-gwang WON

Yong-gwang WON L.S.